

첨부 1 직접사용 대상 장비

☐ 공정 장비목록 (39대)

구분	장비명
1	Maskless Laser Lithography System
2	PE-CVD - 1
3	Dry-Etcher_Ulvac
4	Dry-Etcher_TEL
5	Dry Etcher_Oxide
6	Dry Etcher_Poly Si
7	PR Asher_FEOL - 1
8	PR Asher_FEOL - 2
9	PR Asher_BEOL
10	Wet Station_Organic
11	Wet Station_Acid - 1
12	Wet Station_Acid - 2
13	Spin Dryer
14	Wet Station_Pre Clean
15	CD-SEM
16	Spectroscopic Ellipsometer
17	4 Point Probe - 1
18	3D Profiler
19	Stress Measurement System
20	Optical Microscopes - Photo
21	Optical Microscopes - Etch
22	Optical Microscopes - ThinFilm
23	Optical Microscopes - Diffusion
24	Optical Microscopes - EBL
25	HR FE-SEM (Clean Room)
26	Thickness Measurement_KMAC
27	Probe Station_Power Semiconductor
28	Curve Tracer with Probe Station (in Clean Room)
29	Mask Aligner_MA6
30	Mask Aligner_MA8
31	Mask Aligner ME
32	NEMS Spin Coater
33	NEMS White Wet station - Acid
34	NEMS White Wet station - Organic
35	NEMS Yellow Wet station - Acid
36	NEMS Yellow Wet station - Organic
37	Metal Lift-Off
38	Deep Reactive Ion Etcher(DRIE) - 1
39	E-Beam Evaporator - 1

□ 분석 장비목록 (15대)

구분	장비명
1	High Resolution FE-SEM- I (JSM 7401F)
2	High Resolution FE-SEM-Ⅱ (JSM 7800F with Dual EDS)
3	High Resolution FE-SEM-Ⅲ (Hitachi S-4800)
4	High Resolution FE-SEM-Ⅳ (JSM IT-710HR)
5	Atomic Force Microscope-Ⅱ (Jupiter XR)
6	HR-[S]TEM- I (2100F with Probe Cs-Corrector)
7	HR-[S]TEM -Ⅱ (2200FS with Image Cs-corrector)
8	Focused Ion Beam- I (Helios 600 with TKD)
9	Focused Ion Beam-Ⅱ (Helios 650 with EBSD)
10	Focused Ion Beam-Ⅲ (Helios G3 CX)
11	Focused Ion Beam-Ⅳ (SMI 3050)
12	UV-Vis/NIR Spectrophotometer
13	3D Conforcal Scanning Microscope (3DCSM)
14	High Power XRD (X-Ray Diffractometer)
15	RAMAN (Alpha 300)